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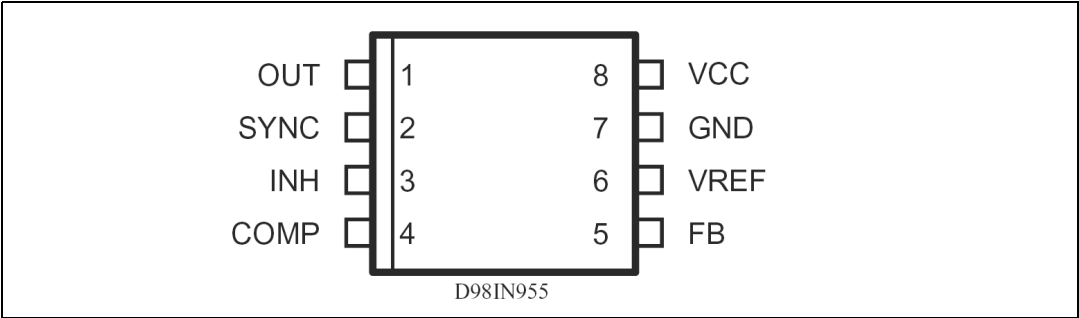
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# 1 Pin settings

## 1.1 Pin connection

Figure 2. Pin connection (top view)



## 1.2 Pin description

Table 1. Pin description

N°	Type	Description
1	OUT	Regulator output.
2	SYNC	Master/slave synchronization.
3	INH	A logical signal (active high) disables the device. If INH not used the pin must be grounded. When it is open an internal pull-up disable the device.
4	COMP	E/A output for frequency compensation.
5	FB	Feedback input. Connecting directly to this pin results in an output voltage of 1.23 V. An external resistive divider is required for higher output voltages.
6	VREF	3.3 V $V_{REF}$ No cap is requested for stability.
7	GND	Ground.
8	VCC	Unregulated DC input voltage.

## 2 Electrical data

### 2.1 Maximum ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_8$	Input voltage	40	V
$V_1$	Output DC voltage	-1 to 40	V
	Output peak voltage at $t = 0.1 \mu\text{s}$	-5 to 40	V
$I_1$	Maximum output current	int. limit.	
$V_4, V_5$	Analog pins	4	V
$V_3$	INH	-0.3 V to $V_{CC}$	
$V_2$	SYNC	-0.3 to 4	V
$P_{TOT}$	Power dissipation at $T_A \leq 60^\circ\text{C}$	2.25	W
$T_J$	Operating junction temperature range	-40 to 150	$^\circ\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^\circ\text{C}$

### 2.2 Thermal data

**Table 3. Thermal data**

Symbol	Parameter	HSOP8 Exposed Pad	Unit
$R_{thJA}$	Maximum thermal resistance junction-ambient	40 <sup>(1)</sup>	$^\circ\text{C/W}$

1. Package mounted on board

### 3 Electrical characteristics

**Table 4. Electrical characteristics**  
( $T_J = 25\text{ }^{\circ}\text{C}$ ,  $V_{CC} = 12\text{ V}$ , unless otherwise specified)

Symbol	Parameter	Test condition		Min	Typ	Max	Unit
V <sub>CC</sub>	Operating input voltage range	V <sub>O</sub> = 1.235 V; I <sub>O</sub> = 2 A	(1)	4		36	V
R <sub>DS(on)</sub>	Mosfet on Resistance		(1)		0.250	0.5	Ω
I <sub>l</sub>	Maximum limiting current	V <sub>CC</sub> = 4.4 V to 36 V		2.5	3	3.5	A
f <sub>s</sub>	Switching frequency		(1)	212	250	280	kHz
				225	250	275	kHz
	Duty cycle			0		100	%
Dynamic characteristics (see test circuit ).							
V <sub>5</sub>	Voltage feedback	4.4 V < V <sub>CC</sub> < 36 V, 20 mA < I <sub>O</sub> < 2 A		1.220	1.235	1.25	V
			(1)	1.198	1.235	1.272	V
h	Efficiency	V <sub>O</sub> = 5 V, V <sub>CC</sub> = 12 V			90		%
DC characteristics							
I <sub>qop</sub>	Total operating quiescent current		(1)		3	5	mA
I <sub>q</sub>	Quiescent current	Duty Cycle = 0; V <sub>FB</sub> = 1.5 V				2.5	mA
I <sub>qst-by</sub>	Total stand-by quiescent current	V <sub>inh</sub> > 2.2 V	(1)		50	100	μA
		V <sub>CC</sub> = 36 V; V <sub>inh</sub> > 2.2 V	(1)		80	150	μA
Inhibit							
	INH threshold voltage	Device ON				0.8	V
		Device OFF		2.2			V
Error amplifier							
V <sub>OH</sub>	High level output voltage	V <sub>FB</sub> = 1 V		3.5			V
V <sub>OL</sub>	Low level output voltage	V <sub>FB</sub> = 1.5 V				0.4	V
I <sub>O source</sub>	Source output current	V <sub>COMP</sub> = 1.9 V; V <sub>FB</sub> = 1 V		200	300		μA
I <sub>O sink</sub>	Sink output current	V <sub>COMP</sub> = 1.9 V; V <sub>FB</sub> = 1.5 V		1	1.5		mA

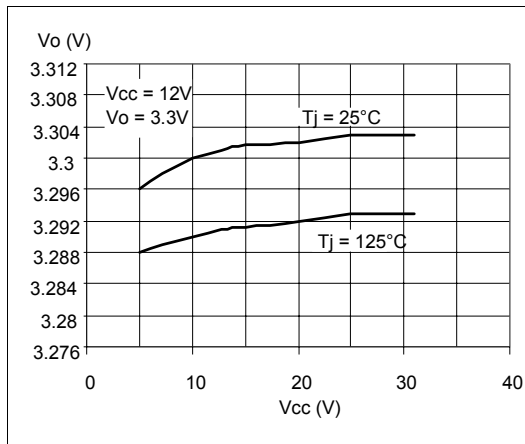
**Table 4. Electrical characteristics (continued)**  
 (  $T_J = 25\text{ }^{\circ}\text{C}$ ,  $V_{CC} = 12\text{ V}$ , unless otherwise specified)

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
$I_b$	Source bias current			2.5	4	$\mu\text{A}$
	DC open loop gain	$R_L = \infty$	50	57		dB
gm	Transconductance	$I_{\text{comp}} = -0.1\text{ mA to } 0.1\text{ mA}$ $V_{\text{COMP}} = 1.9\text{ V}$		2.3		mS
<b>Sync function</b>						
	High input voltage	$V_{CC} = 4.4\text{ V to } 36\text{ V}$	2.5		$V_{\text{REF}}$	V
	Low input voltage	$V_{CC} = 4.4\text{ V to } 36\text{ V}$			0.74	V
	Slave sink current	$V_{\text{sync}} = 0.74\text{ V}^{(2)}$ $V_{\text{sync}} = 2.33\text{ V}$	0.11 0.21		0.25 0.45	 mA
	Master output amplitude	$I_{\text{source}} = 3\text{ mA}$	2.75	3		V
	Output pulse width	no load, $V_{\text{sync}} = 1.65\text{ V}$	0.20	0.35		$\mu\text{s}$
<b>Reference section</b>						
	Reference voltage		3.234	3.3	3.366	V
		$I_{\text{REF}} = 0\text{ to } 5\text{ mA}$ $V_{CC} = 4.4\text{ V to } 36\text{ V}$	(1) 3.2	3.3	3.399	V
	Line regulation	$I_{\text{REF}} = 0\text{ mA}$ $V_{CC} = 4.4\text{ V to } 36\text{ V}$		5	10	mV
	Load regulation	$I_{\text{REF}} = 0\text{ to } 5\text{ mA}$		8	15	mV
	Short circuit current		10	18	30	mA

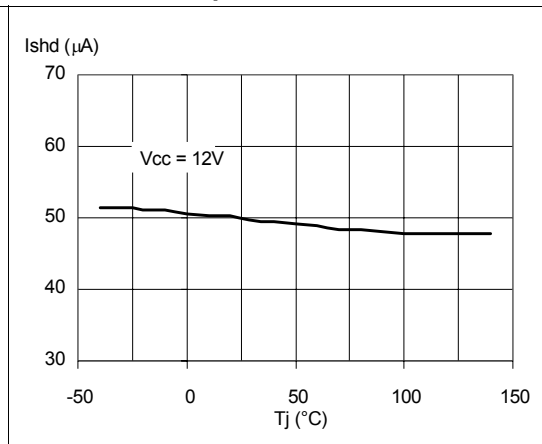
1. Specification Referred to  $T_J$  from  $-40$  to  $125\text{ }^{\circ}\text{C}$ . Specification over the  $-40$  to  $+125\text{ }^{\circ}\text{C}$  Temperature range are assured by design, characterization and statistical correlation.
2. Guaranteed by design.

## 4 Typical characteristics

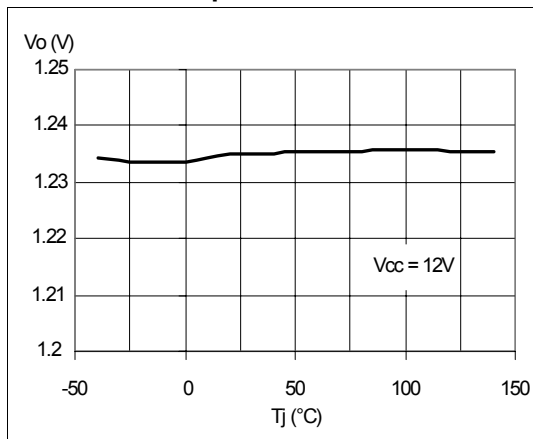
**Figure 3. Line regulation**



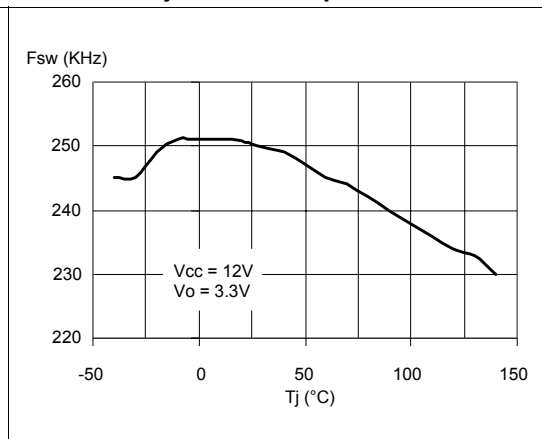
**Figure 4. Shutdown current vs junction temperature**



**Figure 5. Output voltage vs junction temperature**



**Figure 6. Switching frequency vs junction temperature**



**Figure 7. Quiescent current vs junction temperature**

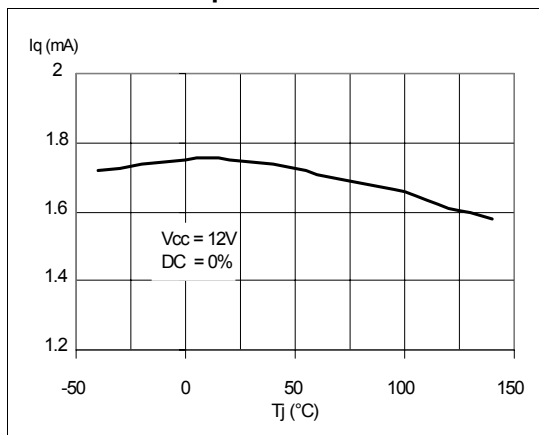


Figure 8. Junction temperature vs output current

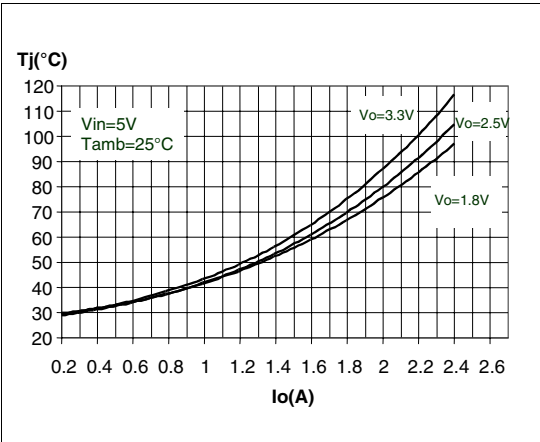


Figure 9. Junction temperature vs output current

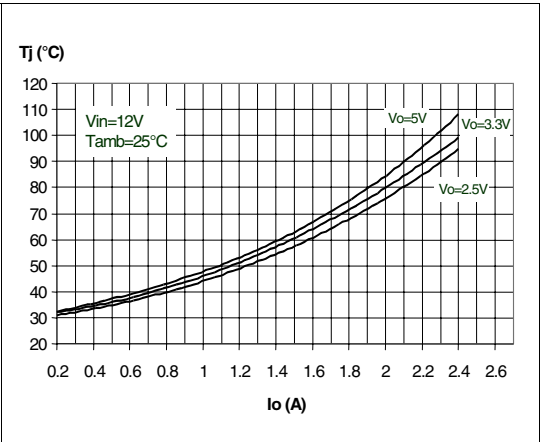


Figure 10. Efficiency vs output current

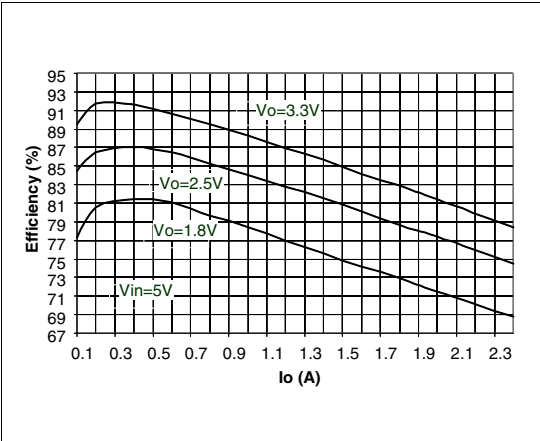
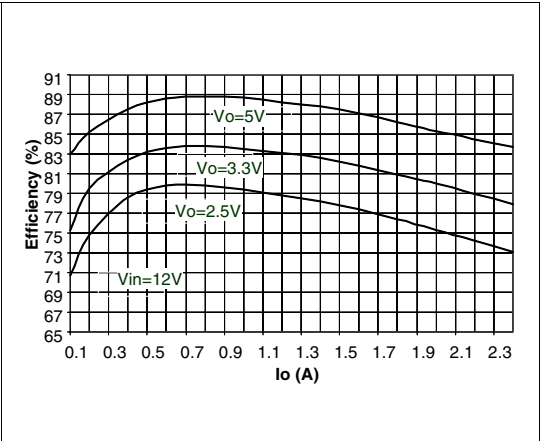


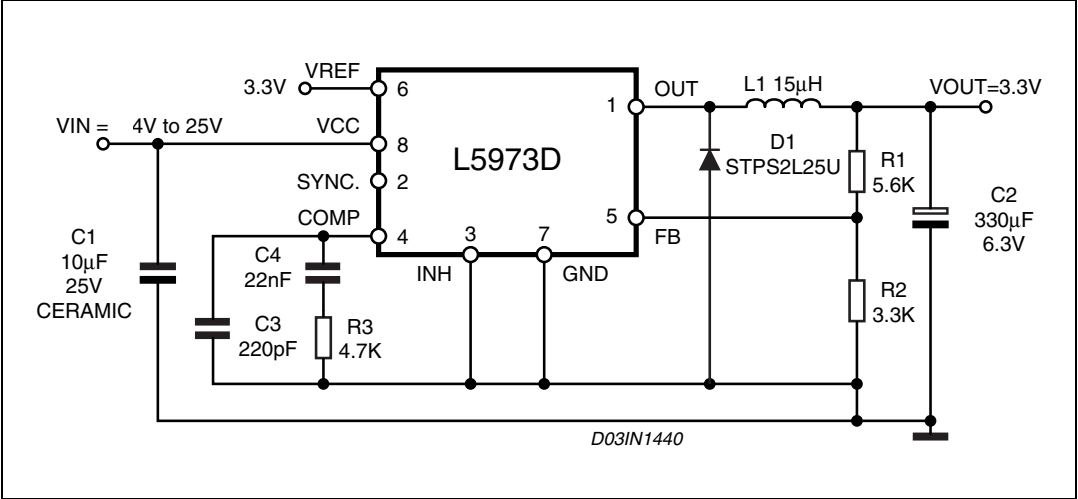
Figure 11. Efficiency vs output current



# 5 Application circuit

In figure 6 is shown the demonstration board application circuit, where the input supply voltage,  $V_{CC}$ , can range from 4 V to 25 V due to the rated voltage of the input capacitor and the output voltage is adjustable from 1.235 V to  $V_{CC}$ .

**Figure 12. Demonstration board application circuit**



**Table 5. Component list**

Reference	Part number	Description	Manufacturer
C1	GRM32DR61E106KA12L	10 µF, 25 V	Murata
C2	POSCAP 6TPB330M	330 µF, 6.3 V	Sanyo
C3	C1206C221J5GAC	220 pF, 5%, 50 V	KEMET
C4	C1206C223K5RAC	22 nF, 10%, 50 V	KEMET
R1		5.6 K, 1%, 0.1 W 0603	Neohm
R2		3.3 K, 1%, 0.1 W 0603	Neohm
R3		4.7 K, 1%, 0.1 W 0603	Neohm
D1	STPS2L25U	2 A, 25 V	ST
L1	DO3316P-153	15 µH, 3 A	COILCRAFT



Figure 13. PCB layout (component side)

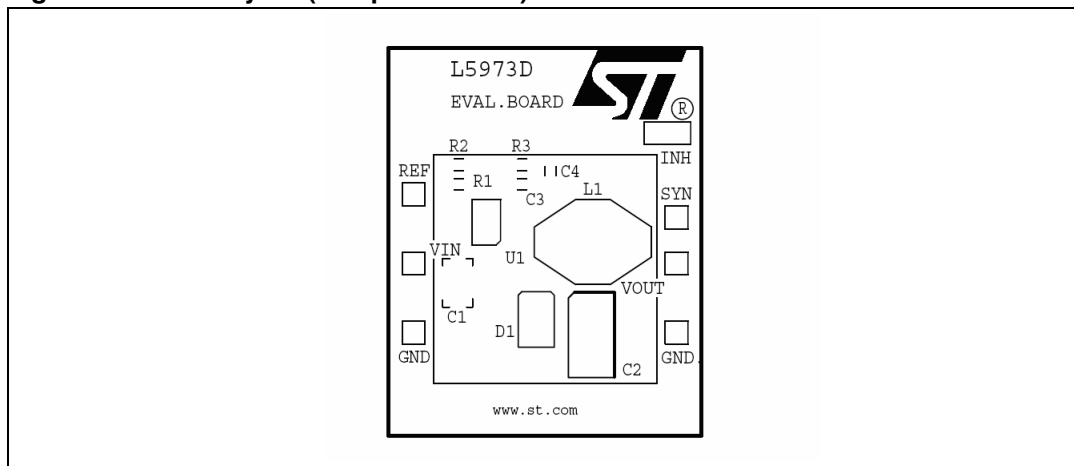


Figure 14. PCB layout (bottom side)

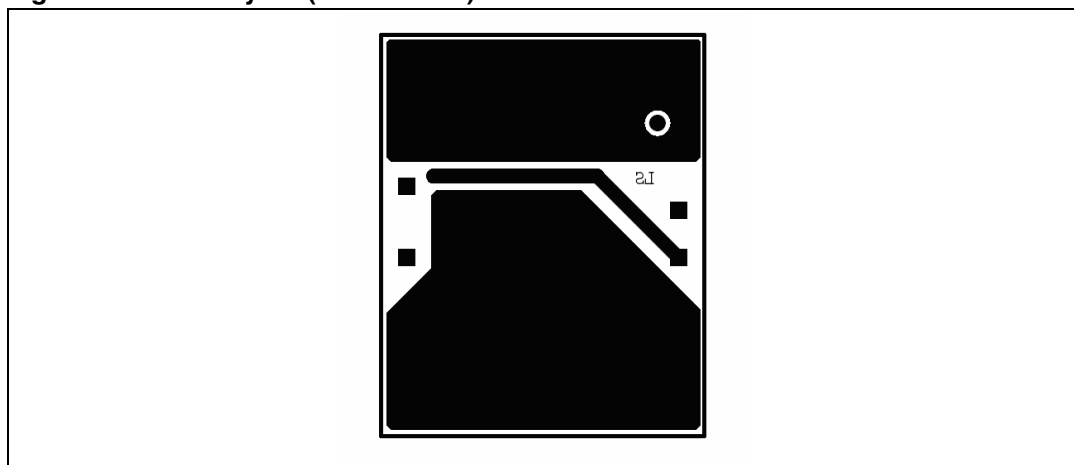
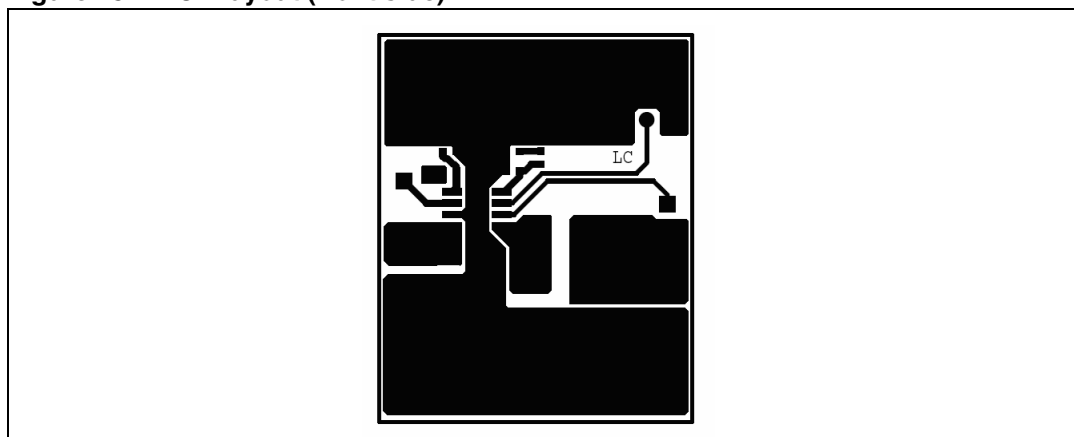


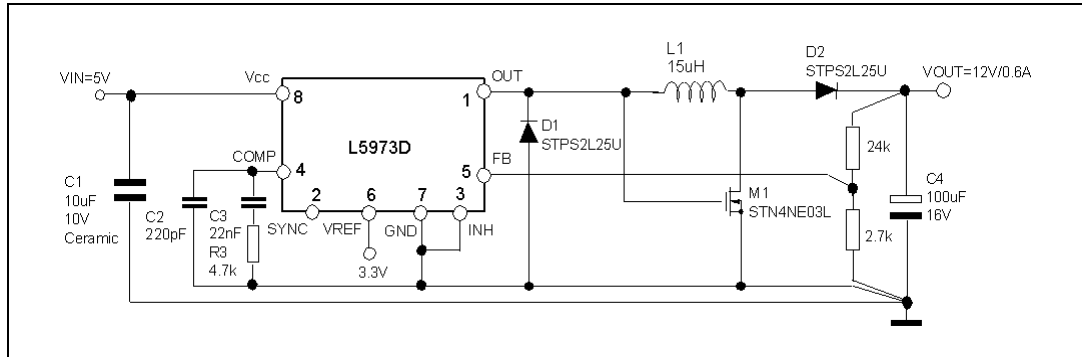
Figure 15. PCB layout (front side)



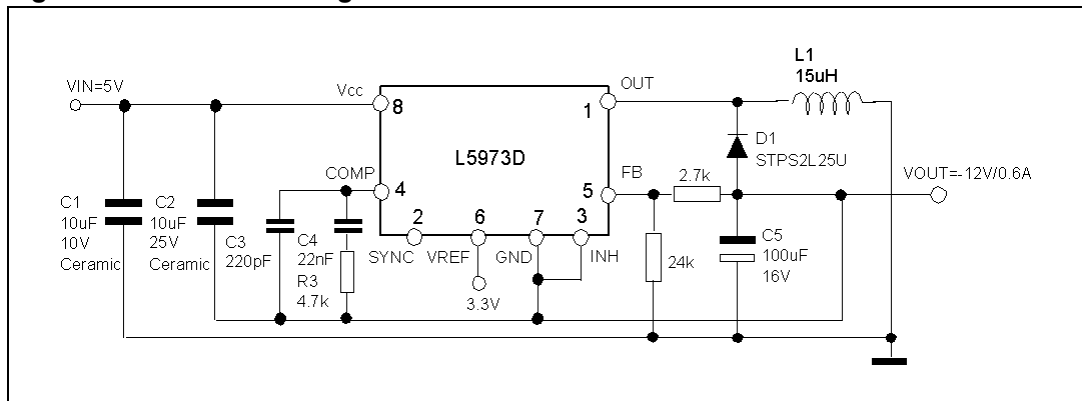
Below some graphs show the  $T_J$  versus output current in different conditions of the input and output voltage and some efficiency measurements.

## 6 Application ideas

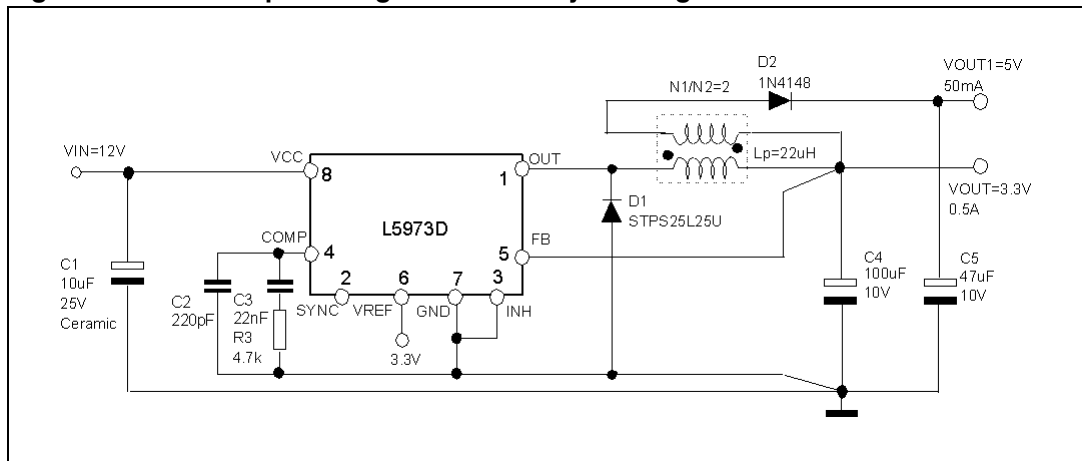
**Figure 16. Positive buck-boost regulator**



**Figure 17. Buck-boost regulator**



**Figure 18. Dual output voltage with auxiliary winding**



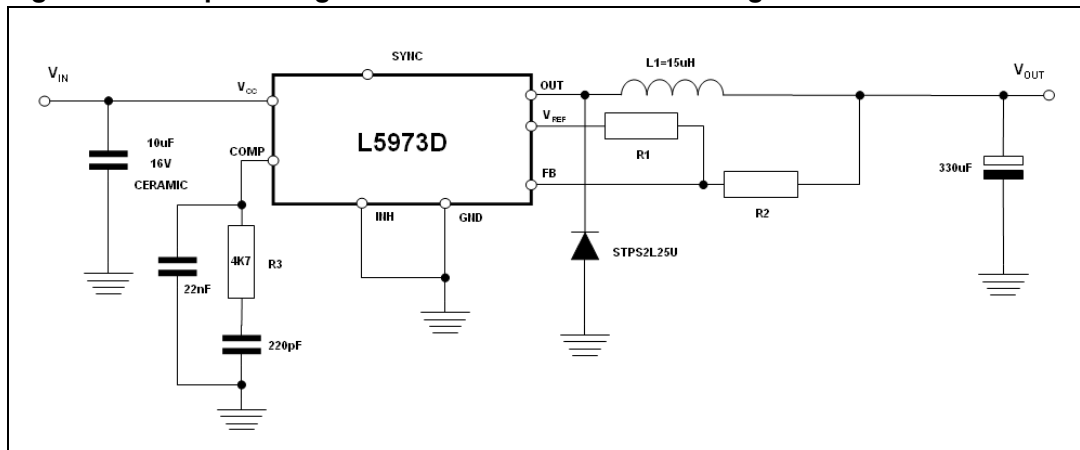
When an output voltage below the internal reference (1.235 V) is required, the circuit reported in the figure 18 can be used. In this case the minimum voltage reachable is 0.6 V and can be easily calculated with the following formula:

$$V_{OUT} = V_{FB} - [(V_{REF} - V_{FB}) \times (R_2 / R_1)]$$

If the load is not present, a resistor connected between  $V_{OUT}$  and GND is required in order to avoid that the voltage across  $C_{OUT}$  increases.

The value of this resistor has to be calculated taking into account that the current flowing through this resistance has to be higher than the current flowing through  $R_2$ .

**Figure 19. Output voltage below the 1.235 V internal voltage reference**



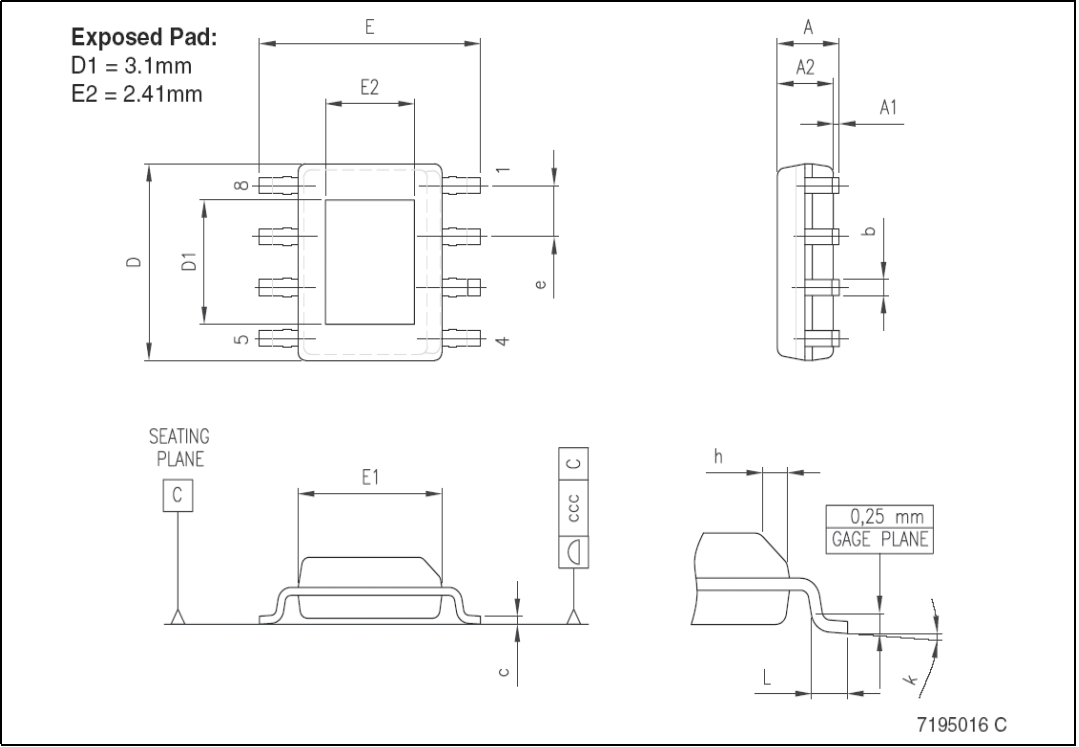
## 7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

Table 6. HSOP8 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A			1.70			0.0669
A1	0.00		0.10		0.00	0.0039
A2	1.25			0.0492		
b	0.31		0.51	0.0122		0.0201
c	0.17		0.25	0.0067		0.0098
D	4.80	4.90	5.00	0.1890	0.1929	0.1969
D1	3	3.1	3.2	0.118	0.122	0.126
E	5.80	6.00	6.20	0.2283		0.2441
E1	3.80	3.90	4.00	0.1496		0.1575
E2	2.31	2.41	2.51	0.091	0.095	0.099
e		1.27				
h	0.25		0.50	0.0098		0.0197
L	0.40		1.27	0.0157		0.0500
k	0° (min), 8° (max)					
ccc			0.10			0.0039

Figure 20. Package dimensions



## 8 Order code

**Table 7. Order code**

Part number	Package	Packaging
L5973D	HSOP8 (Exposed pad)	Tube
L5973D013TR	HSOP8 (Exposed pad)	Tape and reel

## 9 Revision history

**Table 8.** Revision history

Date	Revision	Changes
01-Nov-2005	10	Updated package information
22-May-2006	11	Electrical characteristic <a href="#">Table 4</a> updated, new application idea <a href="#">Figure 19</a> added, new template
13-Nov-2006	12	Typo in order codes
26-Jan-2007	13	Updated <a href="#">Table 4 on page 5</a>
17-Oct-2007	14	Updated <a href="#">Section 5: Application circuit on page 9</a>
24-Oct-2007	15	Updated <a href="#">Table 6 on page 14</a>
07-Jan-2008	16	Updated <a href="#">Table 6 on page 14</a>

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